



Material Content Data Sheet



Sales Product Name		TLS810B1EJ V33		Issued		24. January 2018		
MA#		MA001616846						
Package		PG-DSO-8-52		Weight*		83.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.996	1.19	1.19	11902	11902
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8696	
wire	non noble metal	copper	7440-50-8	29.548	35.31	36.23	353101	362341
	non noble metal	copper	7440-50-8	0.048	0.06	0.06	570	570
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1207
plastics	plastics	epoxy resin	-	4.647	5.55		55528	
	inorganic material	silicondioxide	60676-86-0	45.759	54.68	60.35	546834	603569
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8307	8307
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8658	8658
glue	plastics	epoxy resin	-	0.097	0.12		1163	
	noble metal	silver	7440-22-4	0.292	0.35	0.47	3490	4653
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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